

## 100V N-Channel Power MOSFET

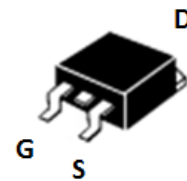
### DESCRIPTION :

- Excellent  $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100%  $\Delta V_{ds}$  Tested
- Pb-Free Lead Plating
- RoHS compliant
- Halogen Free

$V_{DSS}$	100V
$I_D @ V_{GS}=10V$	226A
$R_{DS(ON)_Typ.} @ V_{GS}=10V$	2.5m $\Omega$

### TYPICAL APPLICATIONS :

- Power Management
- Load Switch
- PWM Application



TO-263

### MAXIMUM RATINGS (at $T_C = 25^\circ C$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C=25^\circ C$ $T_C=100^\circ C$	$I_D$	226 143	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	Refer to Fig4	A
Single Pulsed Avalanche Energy <sup>(2)</sup>		$E_{AS}$	1061	mJ
Power dissipation	$T_C=25^\circ C$ $T_C=100^\circ C$	$P_D$	294 118	W
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ C$

- Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.  
2. EAS condition: Starting  $T_J=25^\circ C$ ,  $V_{DD}=50V$ ,  $V_G=10V$ ,  $R_G=25\Omega$ ,  $L=3mH$ ,  $I_{AS}=26.6A$ ,  $V_{DD}=0V$  during time in avalanche.

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta(jA)}$ $R_{\theta(jC)}$	33 0.4	$^\circ C/W$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	$V_{(BR)DSS}$	100			V
Zero Gate Voltage Drain Current VDS = 80 V, VGS = 0 V	$I_{DSS}$			1	uA
Gate-Source Leakage Current VGS = $\pm 20$ V, VDS = 0V	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	$V_{GS(th)}$	2.0	2.9	3.7	V
Drain-Source On-State Resistance VGS = 10V, ID = 20A	$R_{DS(on)}$		2.5	3.3	m $\Omega$
Input capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{iss}$		7651		pF
Output capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{oss}$		2129		pF
Reverse transfer capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{rss}$		37		pF
Gate Resistance f=1MHz, VDS=0 V, VGS=0 V	$R_g$		1.3		$\Omega$
Total Gate Charge VDS= 50V, ID= 20A, VGS= 0 to 10V	$Q_G$		100		nC
Gate to Source Charge VDS= 50V, ID= 20A, VGS= 0 to 10V	$Q_{GS}$		37		nC
Gate to Drain Charge VDS= 50V, ID= 20A, VGS= 0 to 10V	$Q_{GD}$		15		nC
Turn-on delay time VDS=50 V, VGS= 10V, ID= 20A, $R_{GEN}=3\Omega$	$t_{d(ON)}$		27		ns
Rise time VDS=50 V, VGS= 10V, ID= 20A, $R_{GEN}=3\Omega$	$t_r$		29		ns
Turn-off delay time VDS=50 V, VGS= 10V, ID= 20A, $R_{GEN}=3\Omega$	$t_{d(OFF)}$		53		ns
Fall time VDS=50 V, VGS= 10V, ID= 20A, $R_{GEN}=3\Omega$	$t_f$		19		ns

## Body Diode

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = 20A$	$V_{SD}$			1.2	V
Maximum Continuous Body Diode Forward Current	$I_S$			226	A
Maximum Pulsed Body Diode Forward Current	$I_{SM}$			905	A
Revers Recovery Time $I_F = 20A, di/dt = 100A/\mu s$	$T_{rr}$		86		ns
Revers Recovery Charge $I_F = 20A, di/dt = 100A/\mu s$	$Q_{rr}$		206		nC

Typical Performance Characteristics

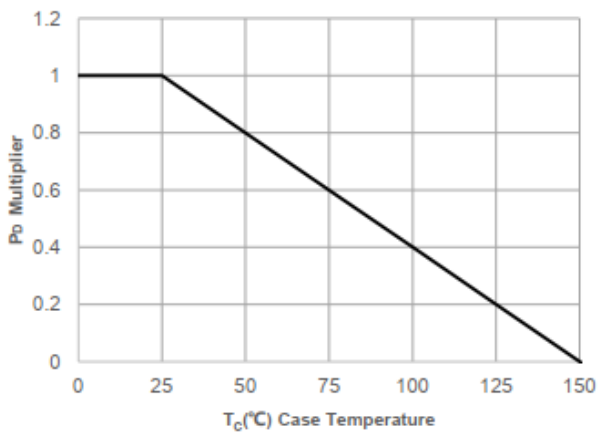


Figure 1. Power De-rating

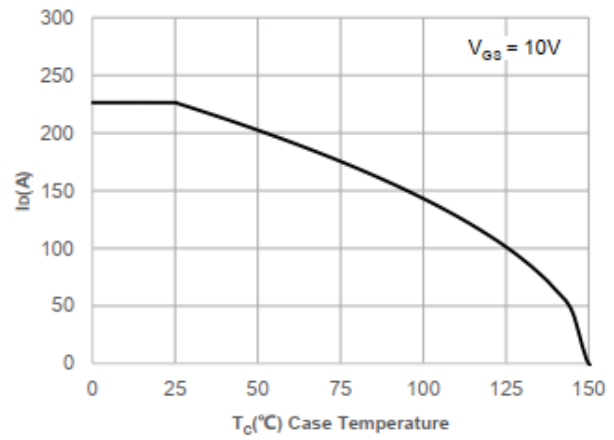


Figure 2. Current De-rating

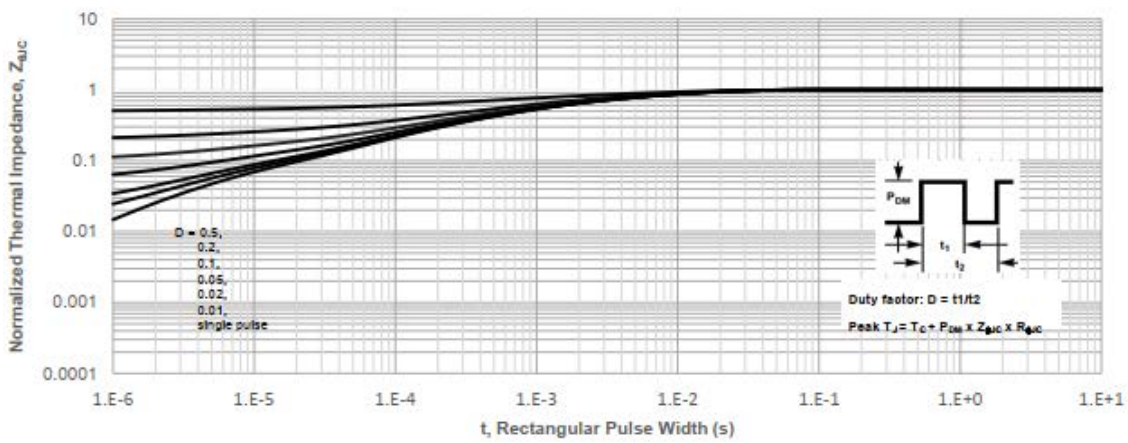


Figure 3. Normalized Maximum Transient Thermal Impedance

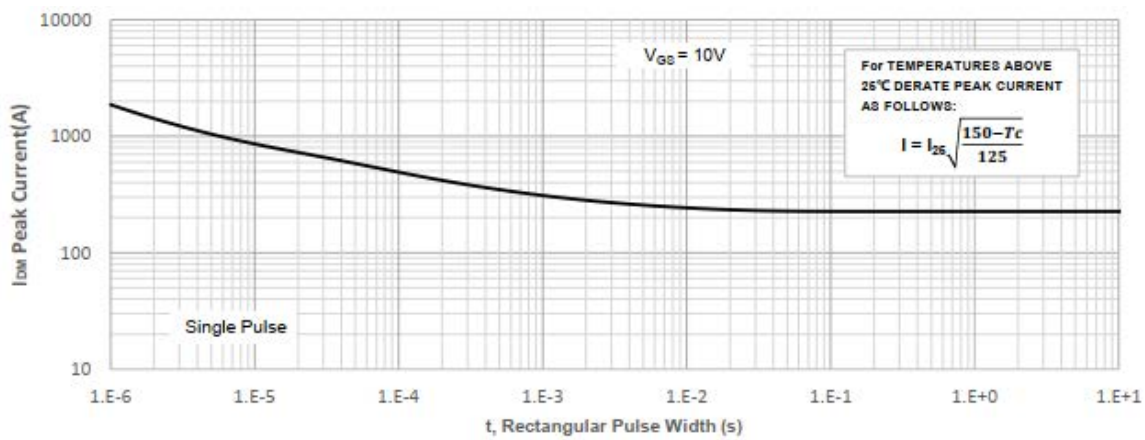


Figure 4. Peak Current Capacity

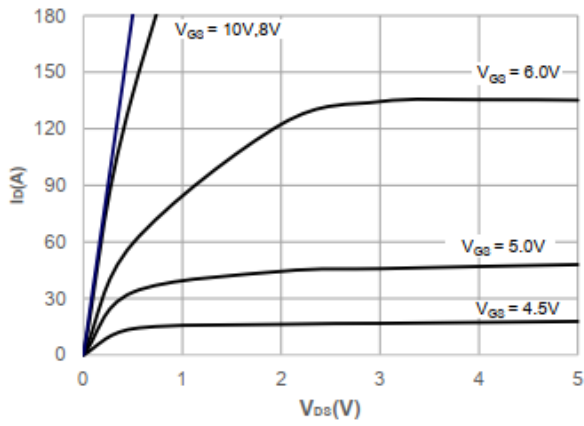


Figure 5. Output Characteristics

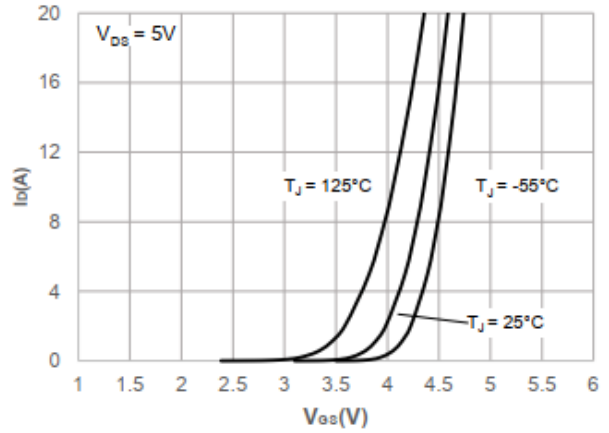


Figure 6. Typical Transfer Characteristics

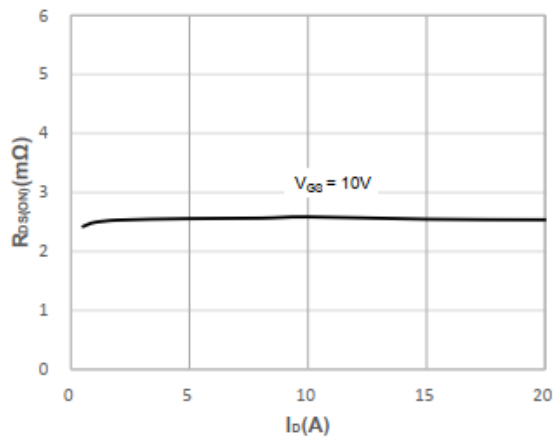


Figure 7. On-resistance vs. Drain Current

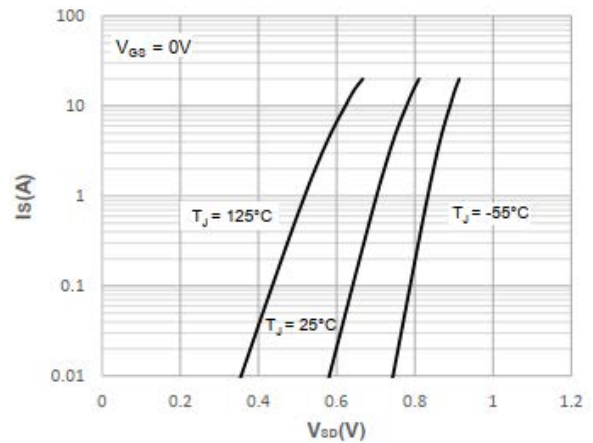


Figure 8. Body Diode Characteristics

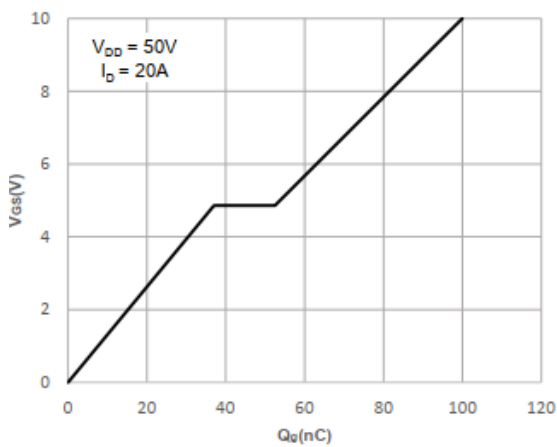


Figure 9. Gate Charge Characteristics

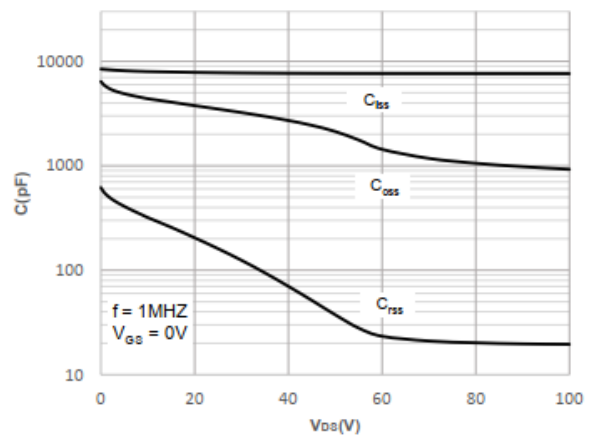


Figure 10. Capacitance Characteristics

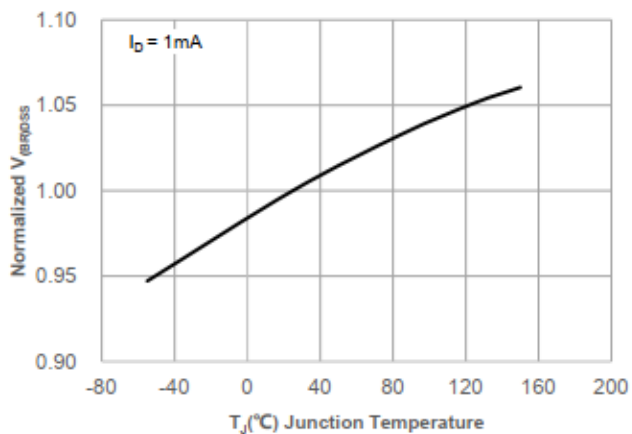


Figure 11. Normalized Breakdown voltage vs. Junction Temperature

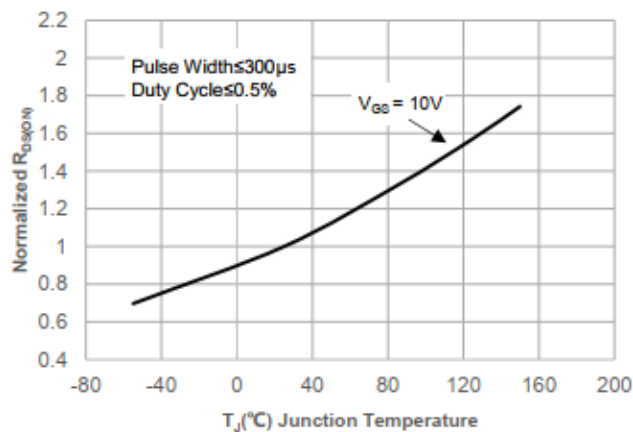


Figure 12. Normalized on Resistance vs. Junction Temperature

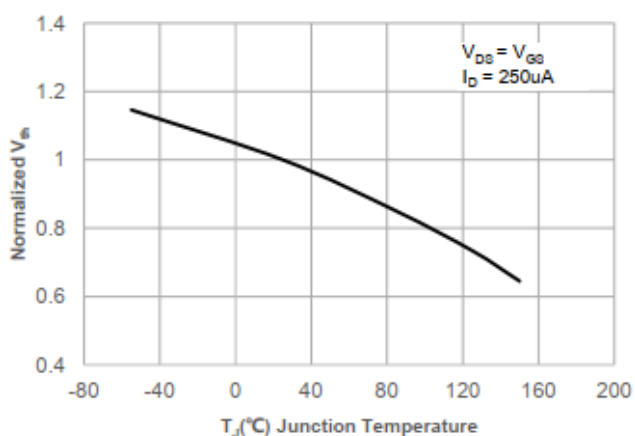


Figure 13. Normalized Threshold Voltage vs. Junction Temperature

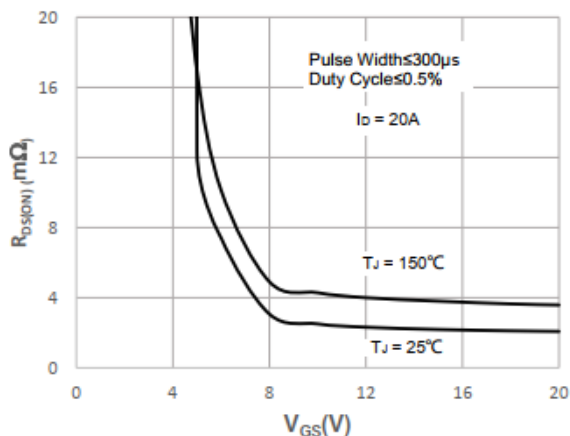


Figure 14. RDS(ON) vs. VGS

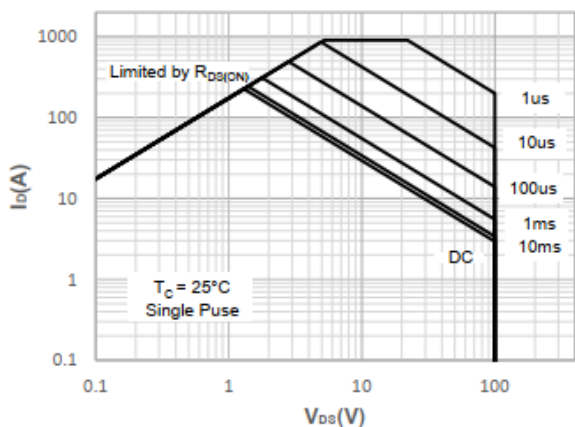
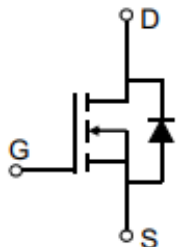
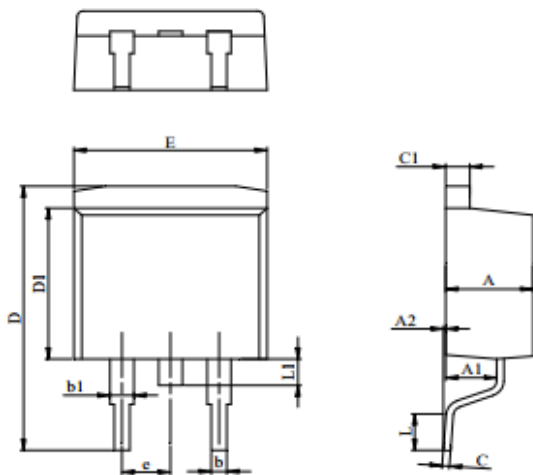


Figure 15. Maximum Safe Operating Area

- Circuit diagram



- Package outlines : Dimensions in (mm)



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	4.24		4.77
A1	2.30		2.89
A2	0.00	0.10	0.25
b	0.70		0.96
b1	1.17		1.70
C	0.30		0.60
C1	1.15		1.42
D	14.10		15.88
D1	8.50		9.60
E	9.78		10.36
L	1.78		2.79
L1			1.75
e		2.54	

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